Grand Venture Technology Limited

(Company Registration Number 201222831E)

NEWS RELEASE

GRAND VENTURE TECHNOLOGY SELECTED AS A PREFERRED SUPPLIER FOR ADVANCED SEMICONDUCTOR PACKAGING EQUIPMENT (THERMAL COMPRESSION BONDING)

- Expansion of GVT's presence in the supply chain of a leading global semiconductor assembly and packaging equipment manufacturer for key technologies like Hybrid Bonding and Thermal Compression Bonding
- Strong multi-year growth prospect driven by the rising demand for end-market applications

Singapore, December 18, 2024 – Mainboard-listed **Grand Venture Technology Limited** (杰纬特科技有限公司, "GVT", or the "Group"), a regional precision manufacturing solutions provider, is pleased to announce that it has been selected as a preferred supplier of High Level Assembly, inclusive of precision parts and components for next generation Thermal Compression Bonding ("TCB") equipment by a leading global semiconductor assembly and packaging equipment manufacturer. This win was enabled by the Group's early engineering engagement and strong collaborative relationship with the customer.

This milestone reinforces GVT's position as a trusted partner for leading semiconductor companies in delivering high-precision, high-performance components and modules that are critical in cutting-edge semiconductor technologies. Our customer's equipment, designed for TCB, plays a vital role in advanced semiconductor packaging that enables the next generation performance of semiconductor chips.

TCB enables advanced semiconductor chips that drive diverse end applications across data centres, graphic cards, AI accelerators, mobile application processors and high bandwidth memory, to address the needs of high-performance computing, advanced graphics, AI workloads and cloud-based solutions.

This represents a major win for the Group, as we anticipate this achievement to play a pivotal role in driving new opportunities and revenue growth momentum starting from 2025 onwards.

The Importance of Thermal Compression Bonding

Thermal Compression Bonding is a critical semiconductor process, especially in the assembly of 2.5D and 3D integrated circuits, flip-chip interconnections, and emerging chiplet architectures. TCB enables the precise placement and bonding of components at extremely fine pitches, which is key to meet the stringent requirements of modern-day electronic devices.

As demand for smaller, faster and more power-efficient devices accelerates across industries such as artificial intelligence (AI), 5G communications, autonomous driving, and high-performance computing, TCB has become essential to ensure: (1) smaller and more compact devices, (2) faster performance, (3) greater durability.

The pivot toward next-generation packaging is driving the growth of the Advanced Packaging ("AP") market. As forecasted by Yole Intelligence, the AP market is expected to grow at a $CAGR_{23\text{-}29}$ of 11% to reach US$69.5 billion in 2029.[1] Additionally, the 2.5D and 3D advanced packaging sector is projected to maintain a robust $CAGR_{23\text{-}29}$ of 18% to reach US$27.6 billion in 2029.[2]

Executive Deputy Chairman Ricky Lee (李添南) said, "We are proud to be chosen as the preferred supplier for this critical packaging technology project. Our track record and expertise in precision engineering, combined with strong manufacturing capabilities, allows us to meet the highest standards of quality, accuracy and reliability that is demanded by our blue-chip customers in the semiconductor industry. The extension of our collaboration with the said customer is a testament to our capabilities of addressing the challenges posed by advent of new technologies and delivering innovative solutions. We will continue to leverage on our advanced engineering competencies and unwavering commitment to quality to deliver top-in-class solutions."

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[1] Yole Intelligence July 2024
[2] Bloomberg Intelligence: Downturn for Chip-Assembly Tools; TCB a Bright Spot

About Grand Venture Technology Limited ("GVT")

Founded in 2012, GVT is a fast-growing and trusted solutions and services provider for the manufacture of complex precision machining, sheet metal components and mechatronics modules. Its manufacturing plants in Singapore, Penang and Johor (Malaysia), and Suzhou (China) are backed by the latest automated manufacturing technologies, Class 10,000 cleanroom facilities and a certified quality management system. The Group's highly experienced and dedicated team of engineering talent serves a strong global network of established partners and suppliers with a wide range of engineering, assembly, testing and product life cycle management solutions.

GVT's portfolio of customers hail from the semiconductor, electronics, analytical life sciences, aerospace, medical and industrial automation industries, and represent some of the largest OEMs in their respective markets. GVT is listed on the Singapore Exchange Mainboard. Visit http://www.gvt.com.sg for more information.

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